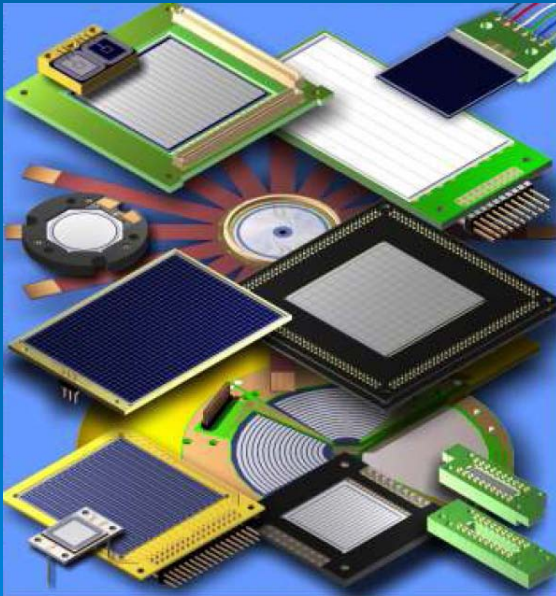


Semiconductor Detectors

Shunji Nishimura



Silicon Detector

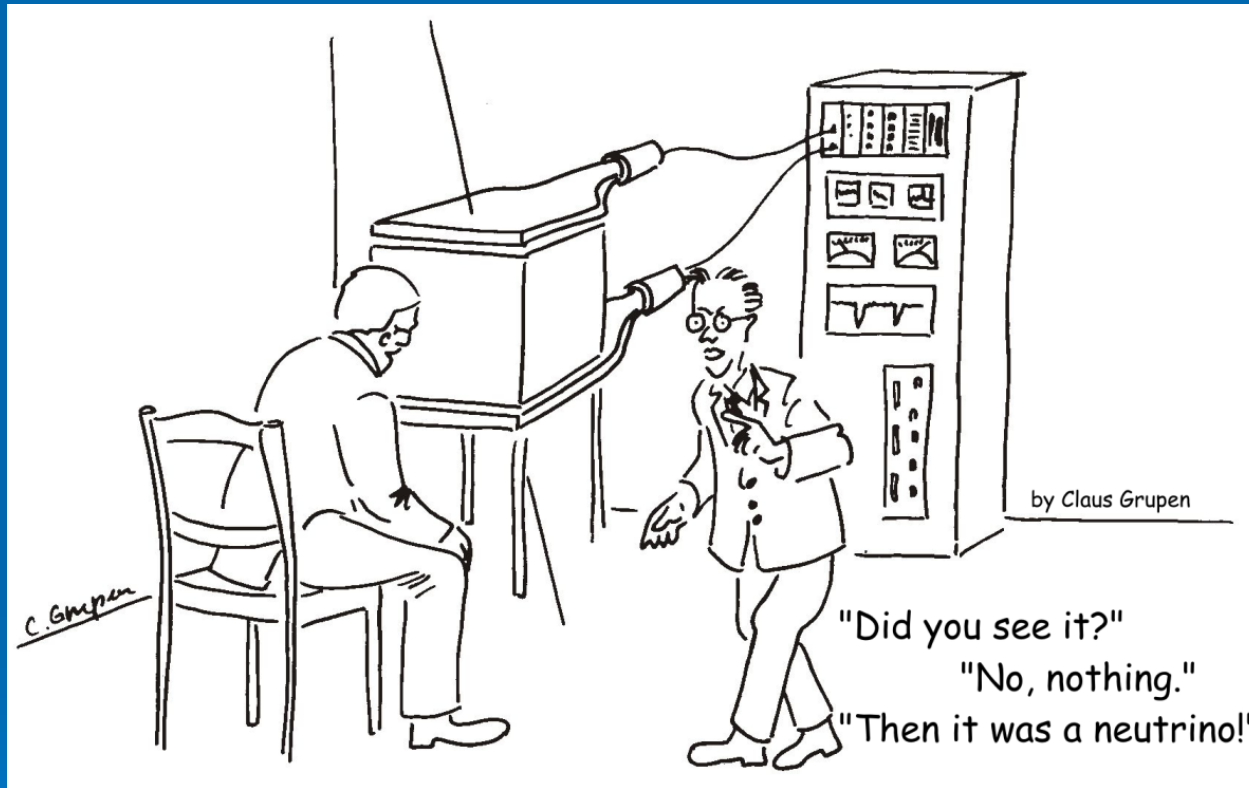


Germanium Detector

Outline of this Lecture

- Introduction
 - Detectors General Requirements
 - Why use semiconductor detectors?
- Basic Principles
 - P-type, N-type
 - Depletion layer
 - Type of detectors
- Performance
 - Energy Measurement
 - Position Measurement
 - Timing Measurement
- Electronics
- Operation : How to use?

Design of Experiments



-Big Project

-Small Project

Experimental setup depends

on what you want to measure for your physics

Detectors General Requirements

[Particle Identification]

- what kind of particles?!

Hadrons

proton, neutron, d, t, ^3He , ...
pion, kaon, ...

Photon

Gamma-ray (γ)

Lepton

Electron (β), Muon (μ), Tau (τ)
Neutrino (ν)

- momentum, direction, time, etc..

Kinematics

Requirements for detectors

➤ Energy measurement

- Energy loss (dE)
- Total energy (E)
- Pulse shape

➤ Position measurement

- $(X, Y, Z) \rightarrow$ Tracking
- $B\rho \rightarrow$ Momentum (p)

➤ Timing measurement

- Timing (velocity β)
- High counting rate (dN/dt)

➤ Count measurement

- Sensitivity to particle (ϵ)
- Insensitive to background (S/N)
- Radiation hardness

There are many types of detectors.

- Scintillation detector (Tamagawa-san)
- Gas detector
- ➡ - Semiconductor detector

→ Is there a perfect detector ?!

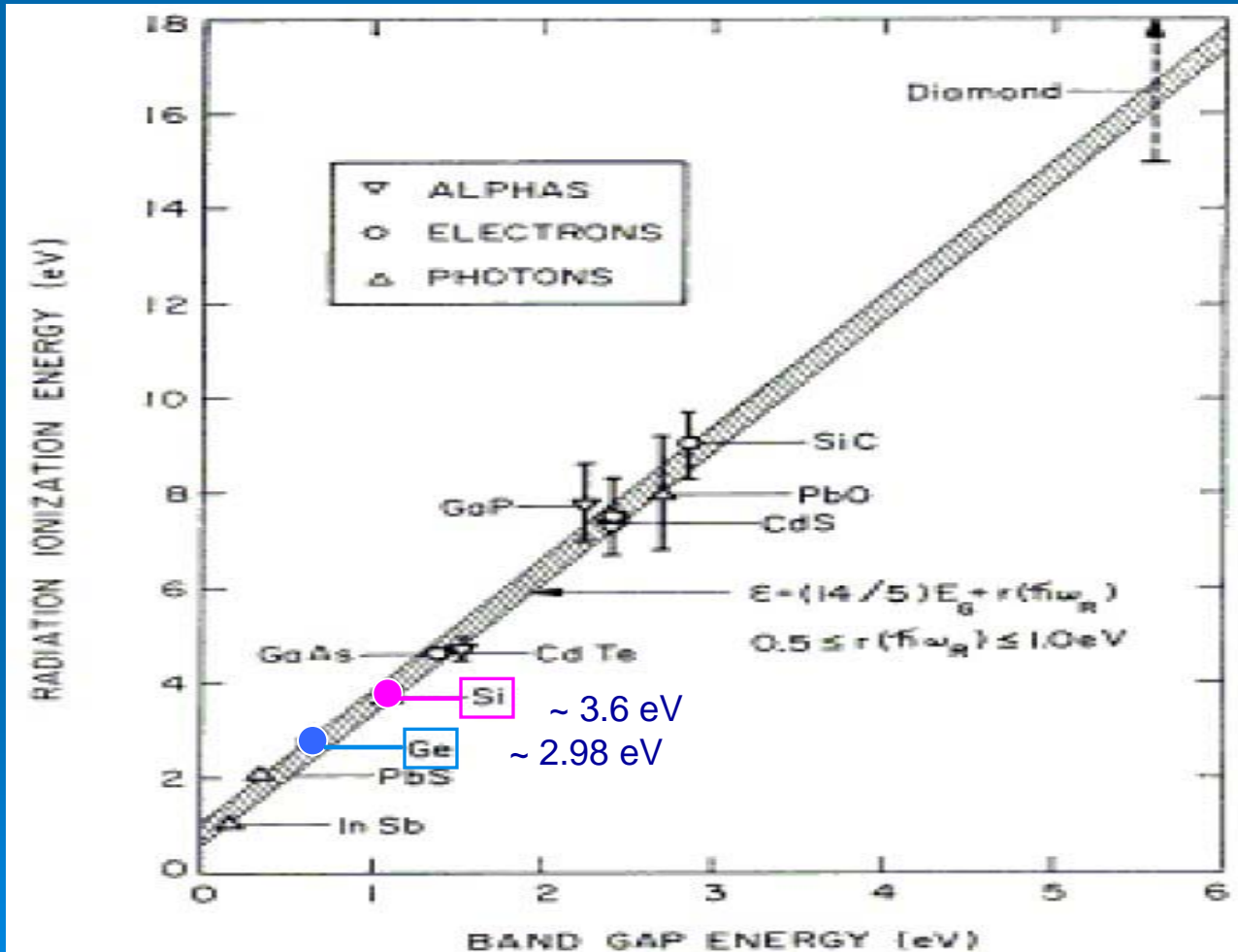
What is the advantage of semiconductor detector?

Characteristics of Semiconductor

- **Low ionization energy**
 - good signal
- **Long mean free path**
 - good charge collection efficiency
- **High mobility**
 - fast charge collection
- **Si ... Lower Z = 14**
 - low multiple scattering
 - Little cooling
- **Ge .. Higher Z = 32**
 - higher stopping power
 - Cooling is required.

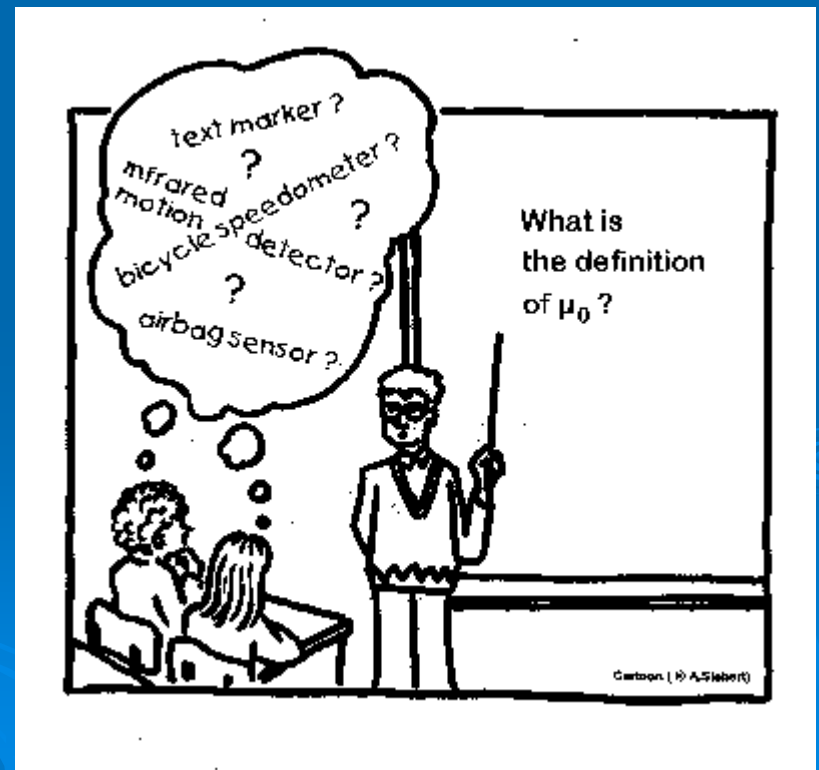
Detector	Ionization energy I (eV)	Energy resolution @ 5MeV $2.35/\sqrt{(5 \times 10^6/I)}$
Scintillation	100 ~ 500	1.1 ~ 2.4 %
Gas	30	0.6 %
Semiconductor	3	0.2%

Energy required for creation of an electron-hole pair



Silicon:
The basic ingredients
are ridiculously cheap

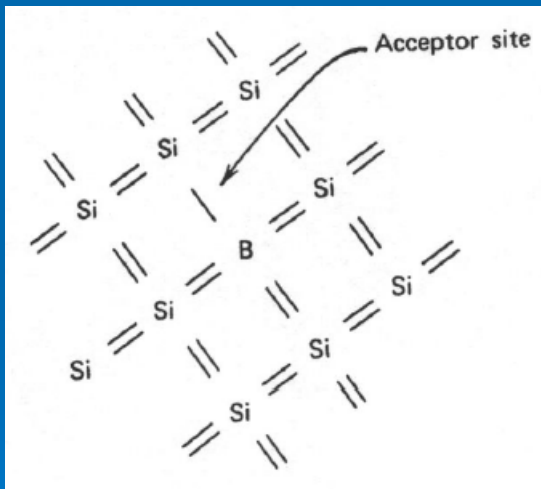
Basic Principles



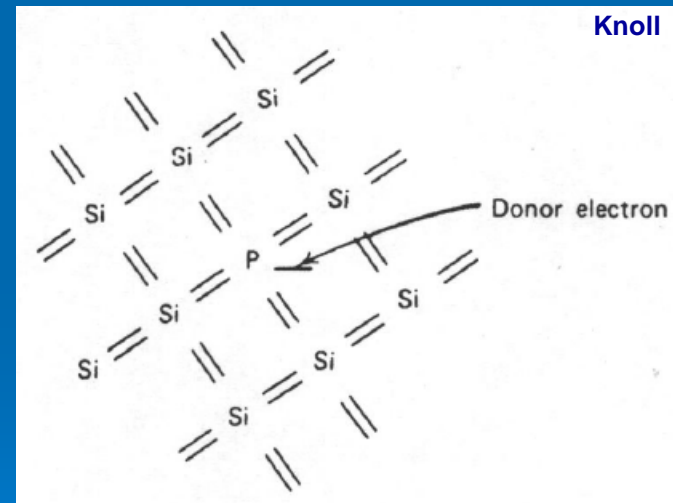
Basic Principles

[To dope the silicon with impurities]

Boron doping (p-type)
holes are majority carriers

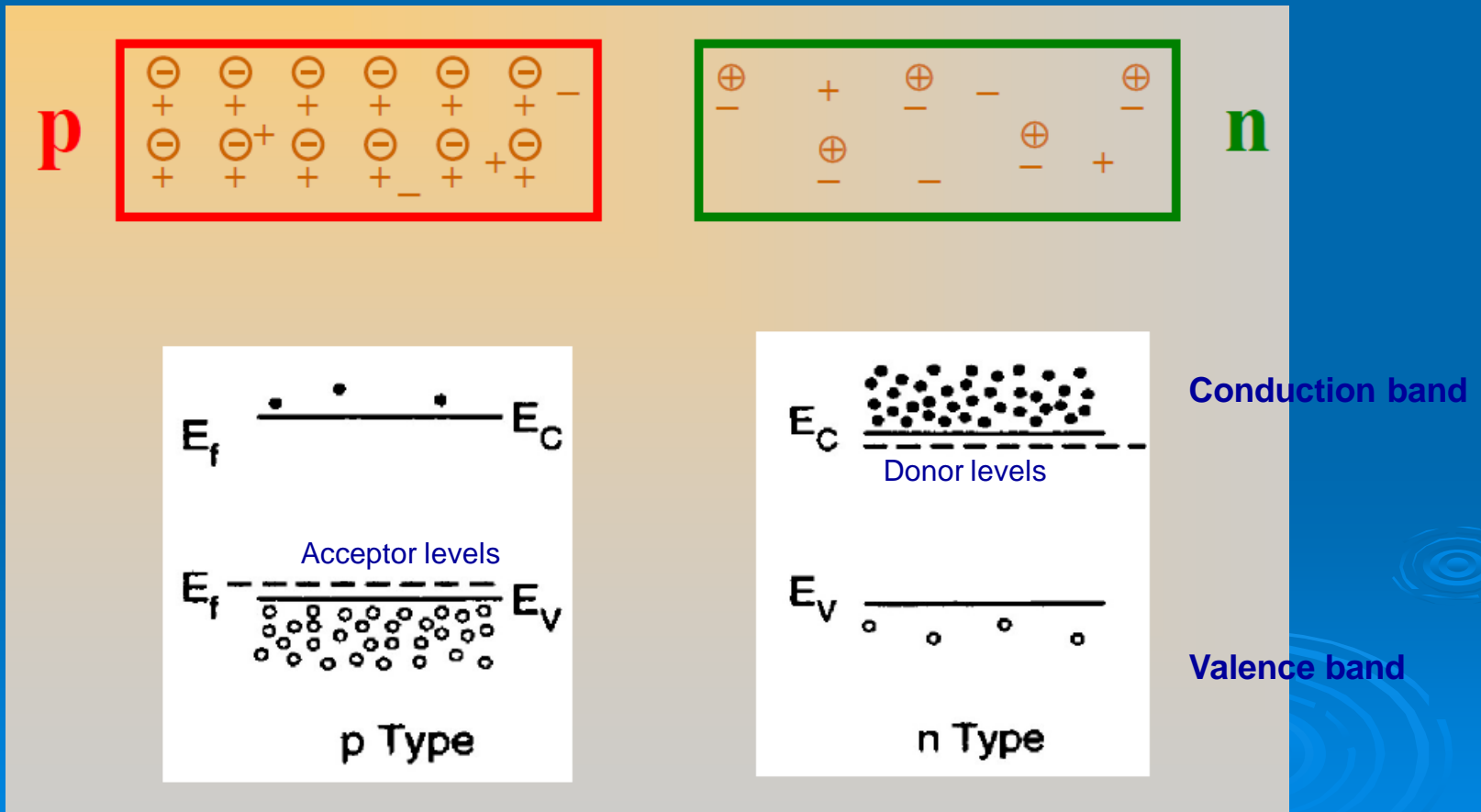


Phosphorus doping (n-type)
electrons are majority carriers



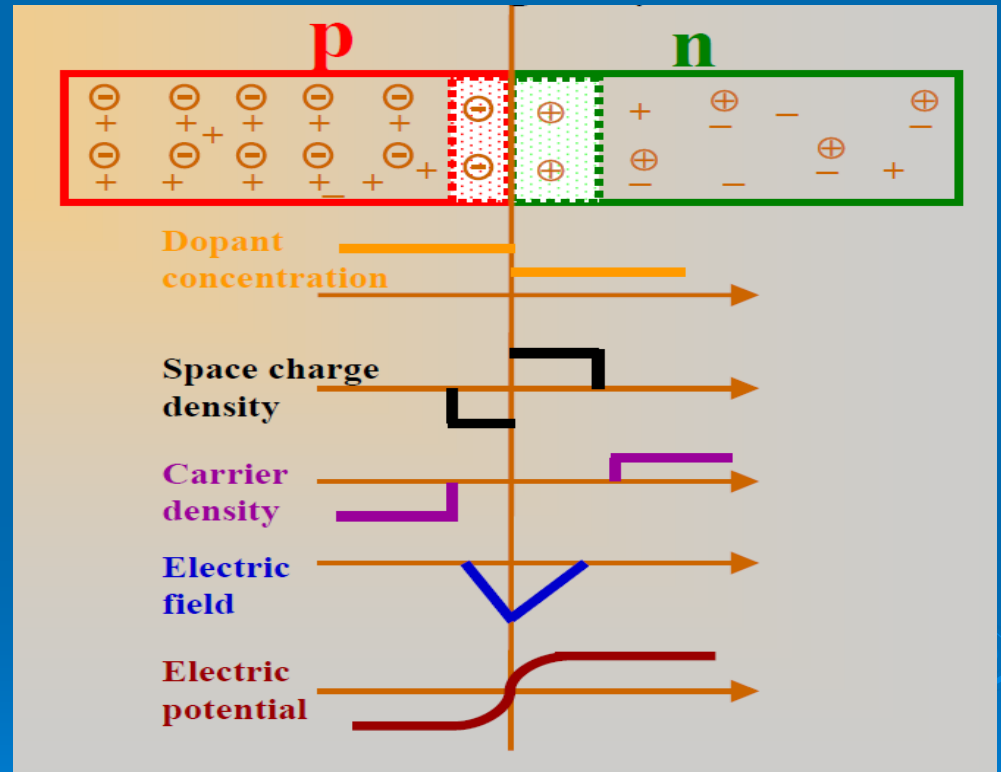
Basic Principles

➤ Now we can construct a p-n junction



Basic Principles

Now for the magic part !

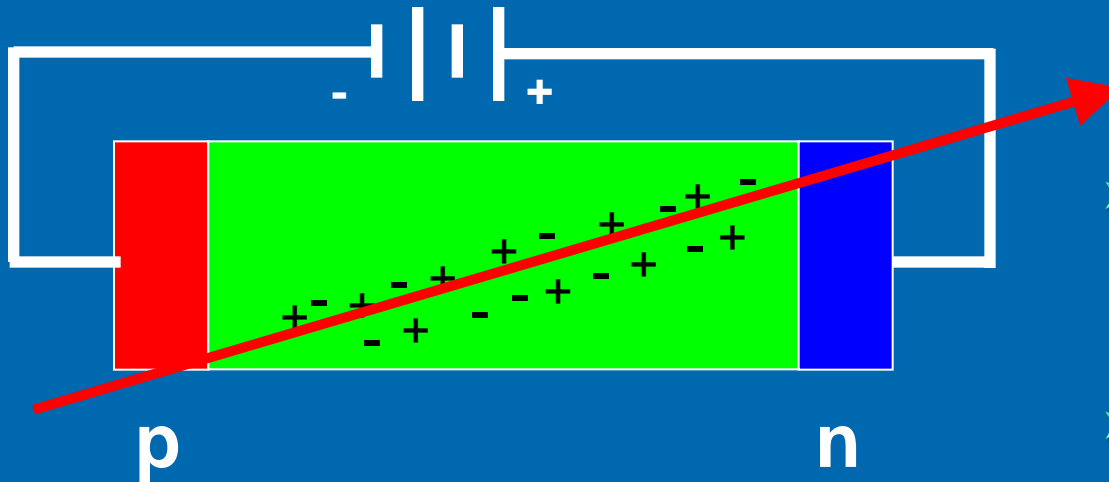


When brought together to form a junction, the majority diffuse carriers across the junction. The migration leaves a region of net charge of opposite sign on each side, called the space-charge region or depletion region. The electric field set up in the region prevents further migration of carriers.

P. Collins (CERN)

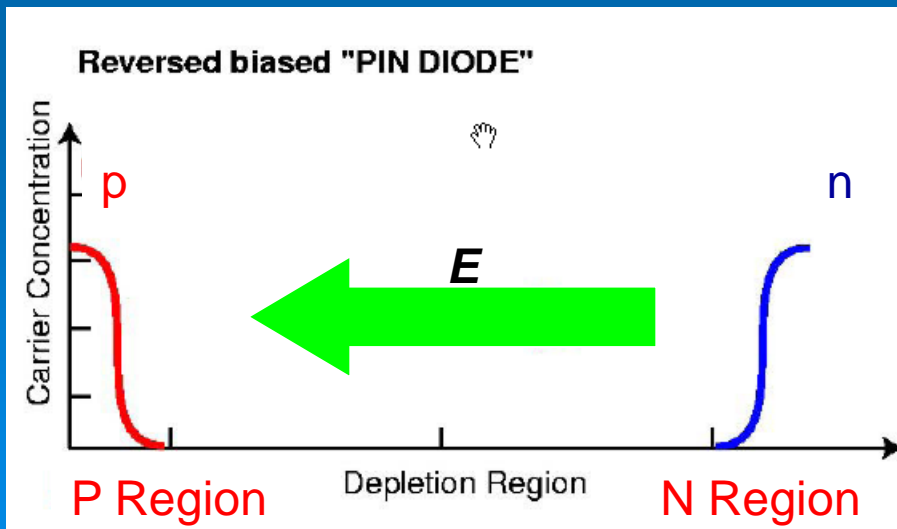
Basic Principles

[Semiconductor structure]



➤ Use ionization signal left behind by charged particle passage.

➤ Ionization produces electron(e)-ion(h) pairs, use electric field to drift the e and h to the oppositely charged electrodes.



➤ Si needs 3.6eV to produce one e-h pair.

Depletion zone

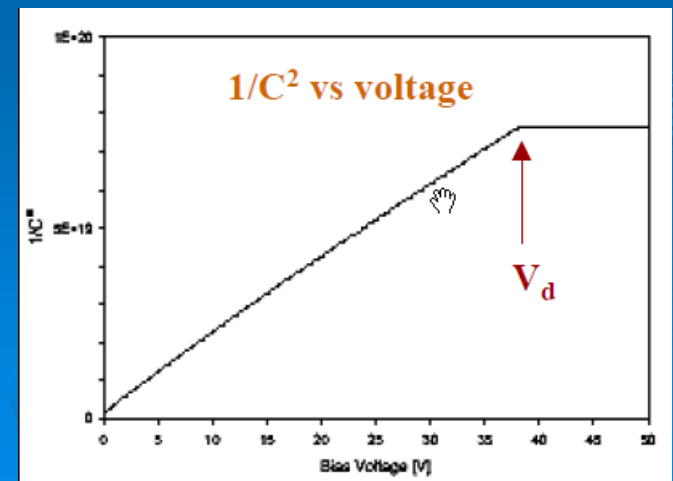
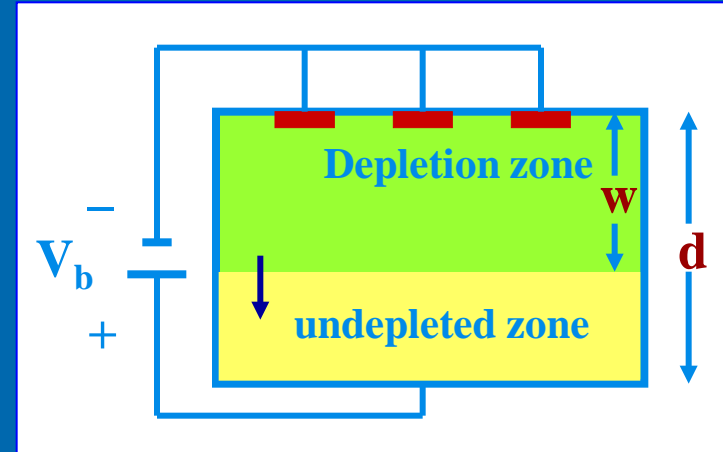
➤ Depletion zone

$$w = \sqrt{2\epsilon\rho\mu V_b}$$

where $\rho = 1/q\mu N$ for doped material and N is the doping concentration (q is always the charge of the electron)

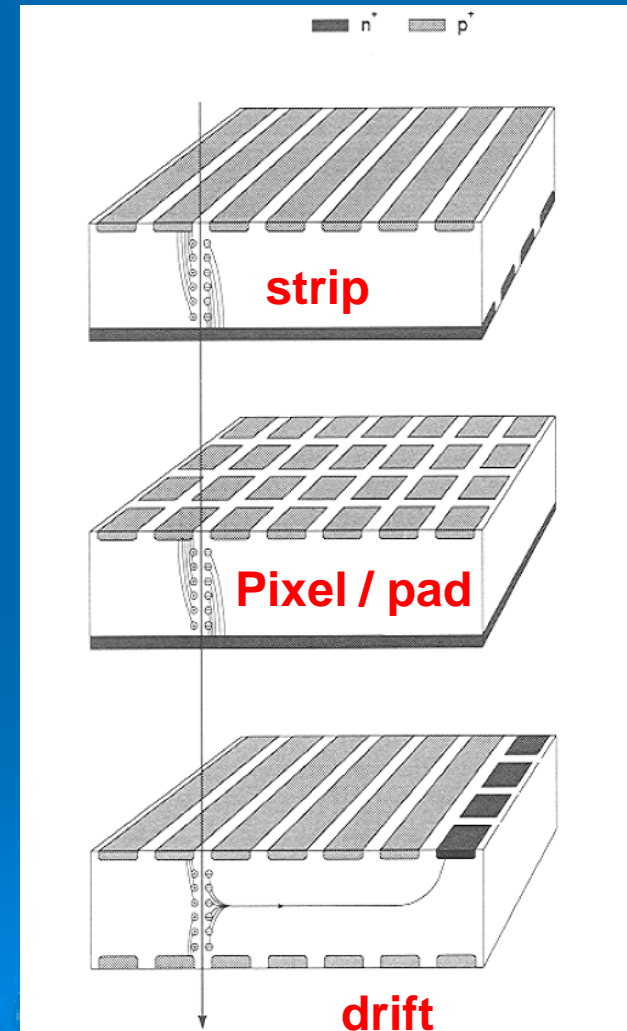
➤ The voltage needed to completely deplete a device of thickness d is called the depletion voltage, V_d

$$V_d = d^2 / (2\epsilon\rho\mu)$$

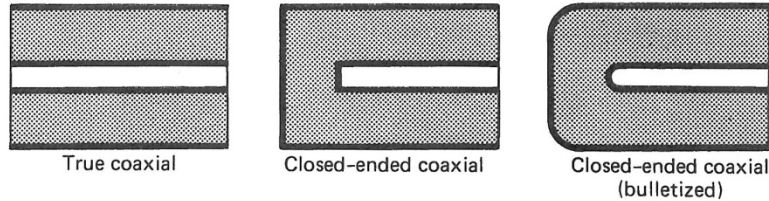


Types of Silicon detectors

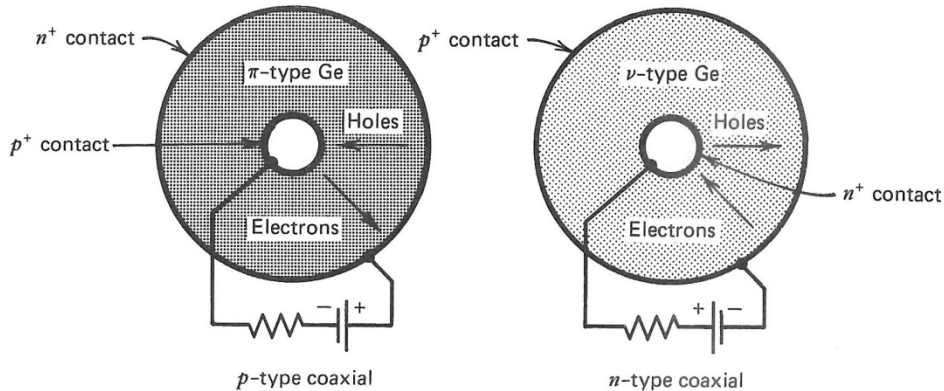
- Strip devices
 - High precision
 - Large active area
 - Single-sided or Double-sided
- Pixel devices
 - True 2-D measurement
 - Small areas, but high track density
- Pad devices
(Big pixels / wide strips)
 - Pre-shower and calorimeters
- Drift devices



Types of Ge-detectors



— represents electrical contact surface

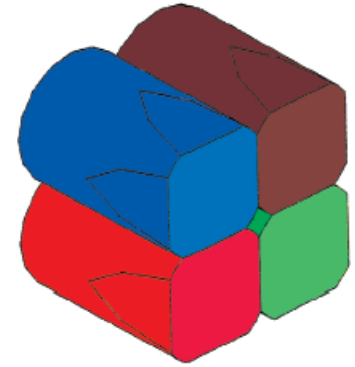


Strip Ge detector

Figure 12.3 At the top are shown the three common shapes of large-volume coaxial detectors. Each represents a cross-sectional view through the axis of a cylindrical crystal. The outer electrode is extended over the flat front (left) surface in both closed-ended cases. Cross sections perpendicular to the cylindrical axis of the crystal are shown at the bottom. The HPGe material may be either high-purity p or n type. The corresponding electrode configurations are shown for each type.

Clover Detector

4 crystals

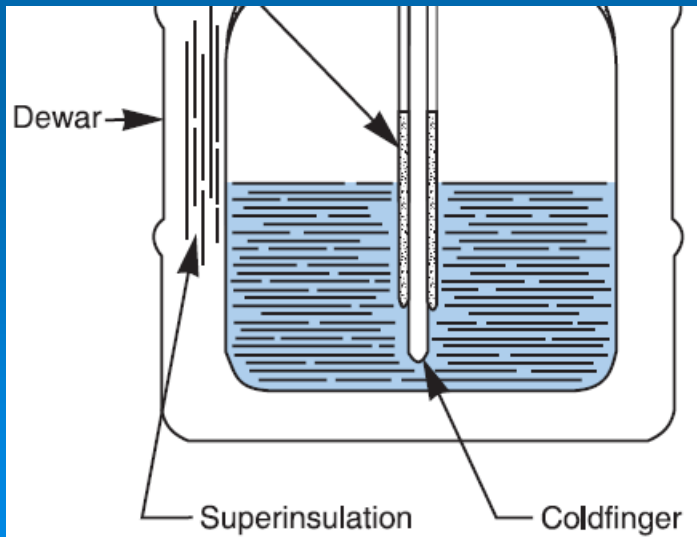


EUROGAM CLOVER

^{60}Co	{	FWHM	: 4 x 2,15 keV
		ϵ_r	: 4 x 20%
		ϵ_r add-back	: 130%



Liquid Nitrogen for cooling

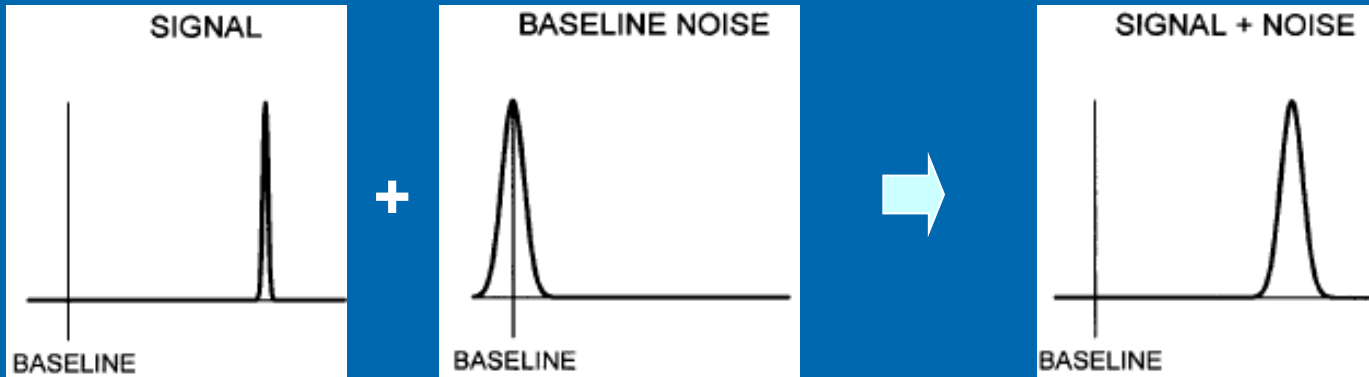


Performance I

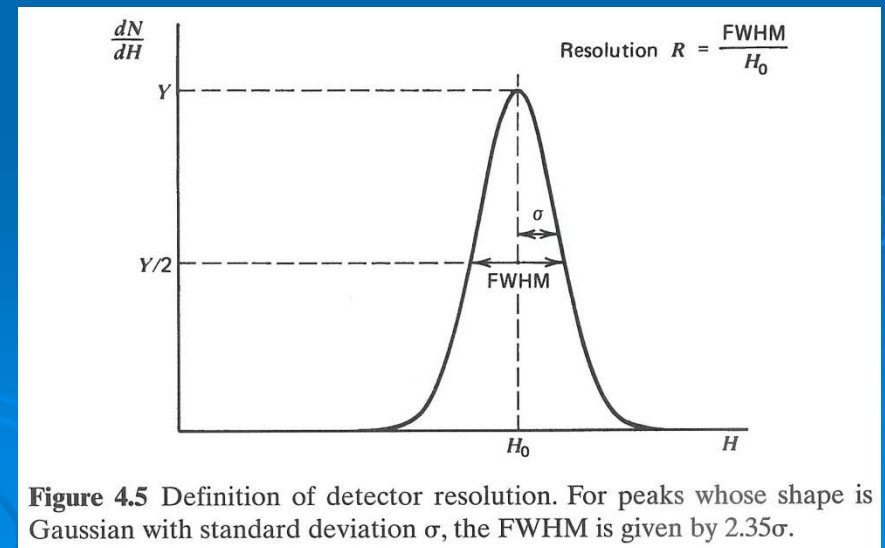
Energy Resolution



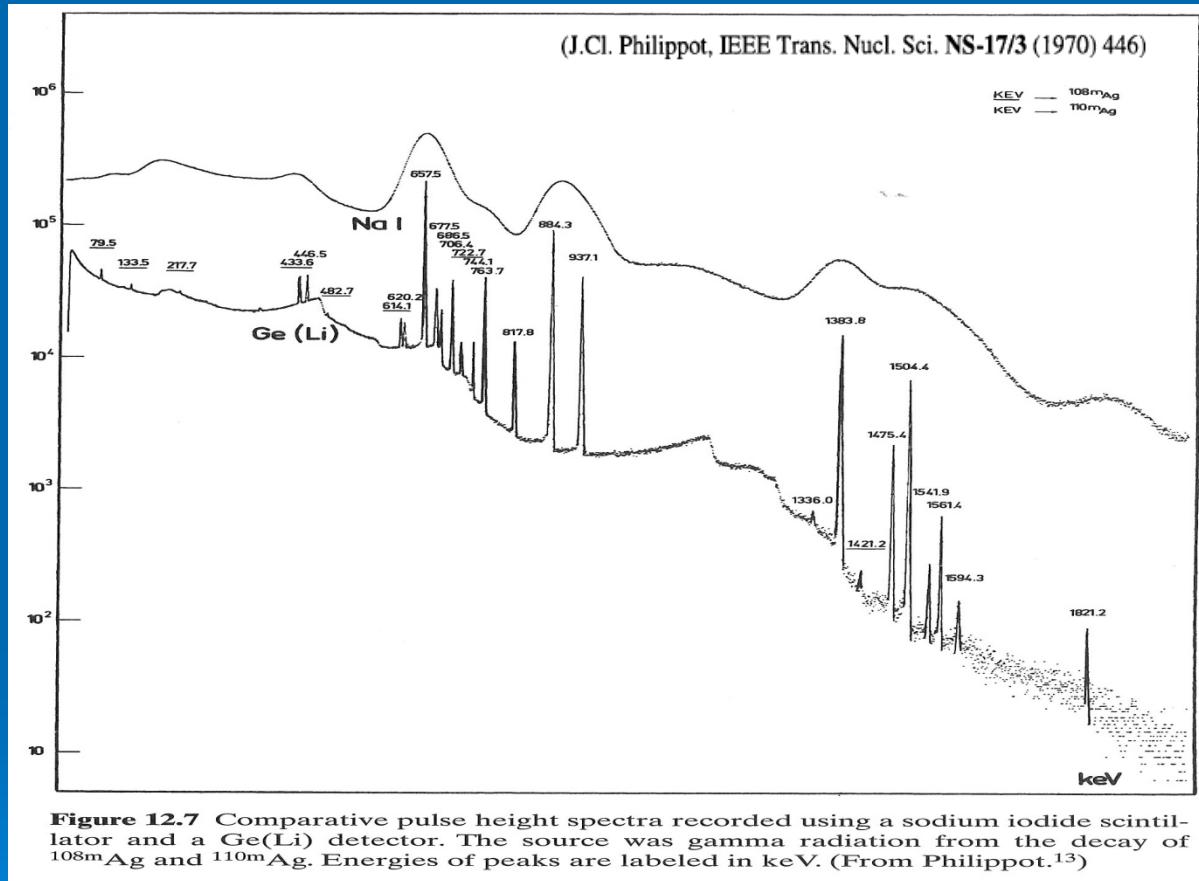
Energy Resolution



If Signal Variance \ll Baseline Variance
→ Electronics (baseline) noise
critical for resolution



Energy Resolution : NaI(Tl) vs Ge



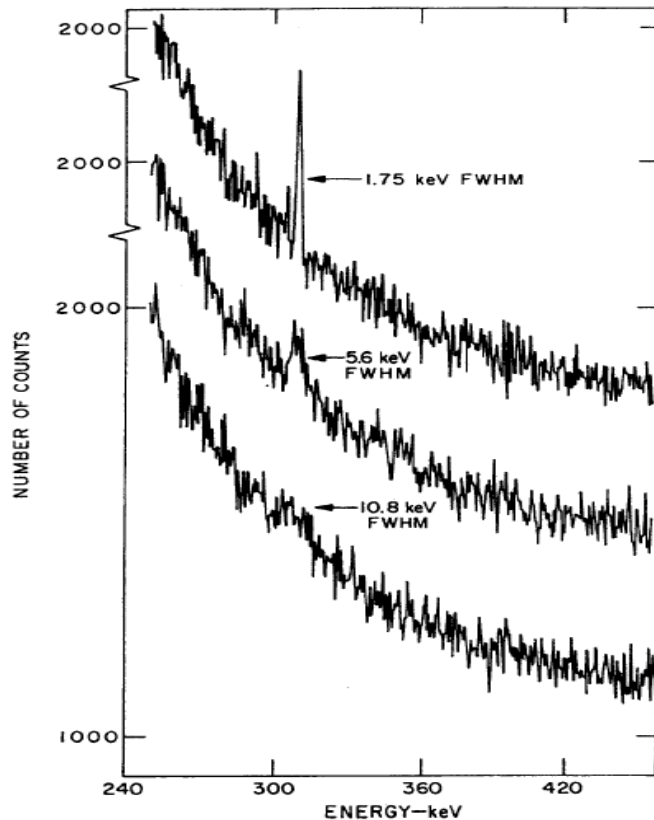
Semiconductor detector

→ Excellent detector for energy measurement !!

Energy Resolution

[Signal to Background Ratio (S/N)]

Signal to background ratio improves with better resolution
(signal counts in fewer bins compete with fewer background counts)



G.A. Armantrout, *et al.*, IEEE Trans. Nucl. Sci. NS-19/1 (1972) 107

→ Good Energy Resolution
→ Higher Statistics

We can extract

- precise peak position,
- and find NEW Peaks!!

Particle Identification

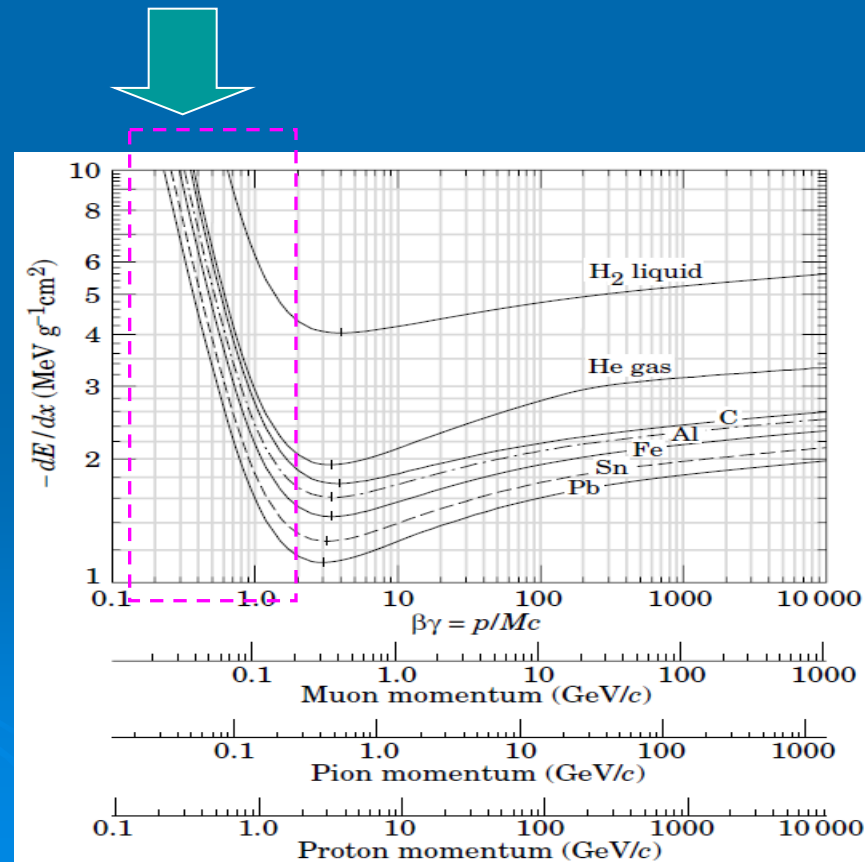
[Use Difference of Stopping Power]

$$p = m_0 \beta \gamma$$

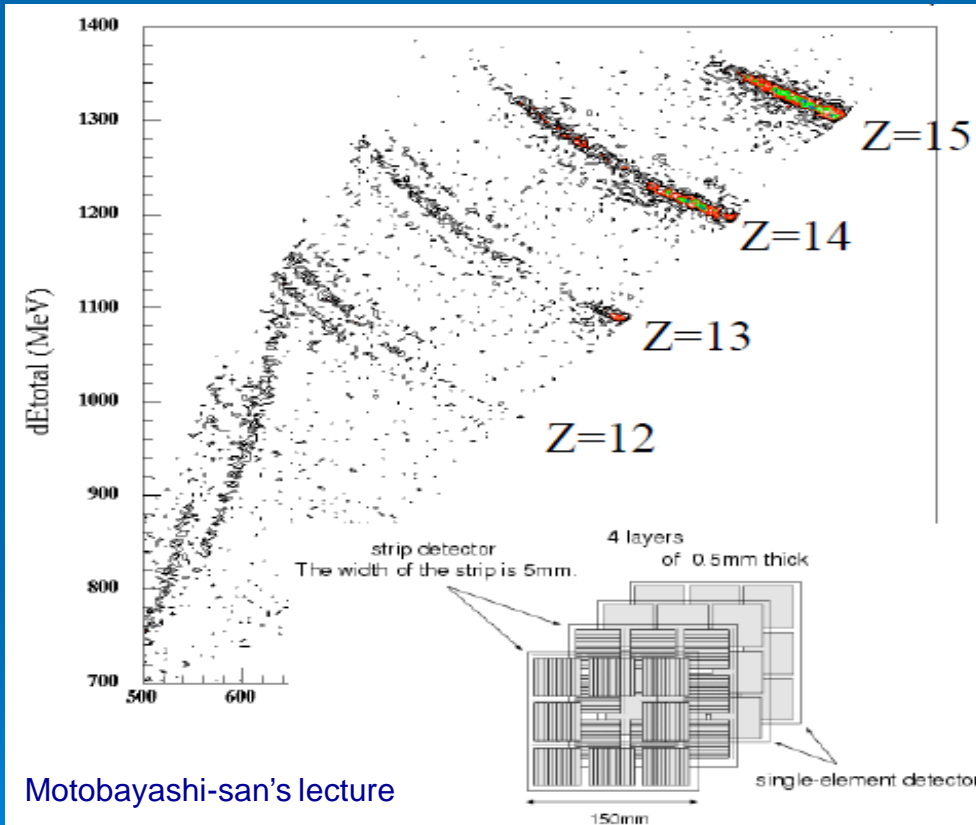
$$\frac{dE}{dx} \propto \frac{1}{\beta^2} \ln(\beta^2 \gamma^2)$$

Knowing p and β gives m

For very low momenta, we can exploit the bethe-bloch formula for particle identification



Particle Identification [dE-E Correlation]



Motobayashi-san's lecture

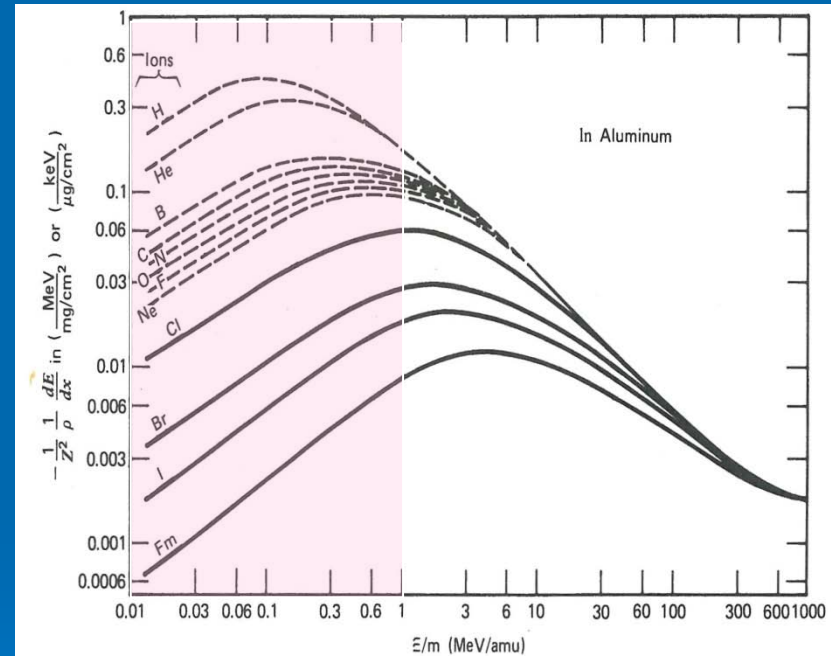
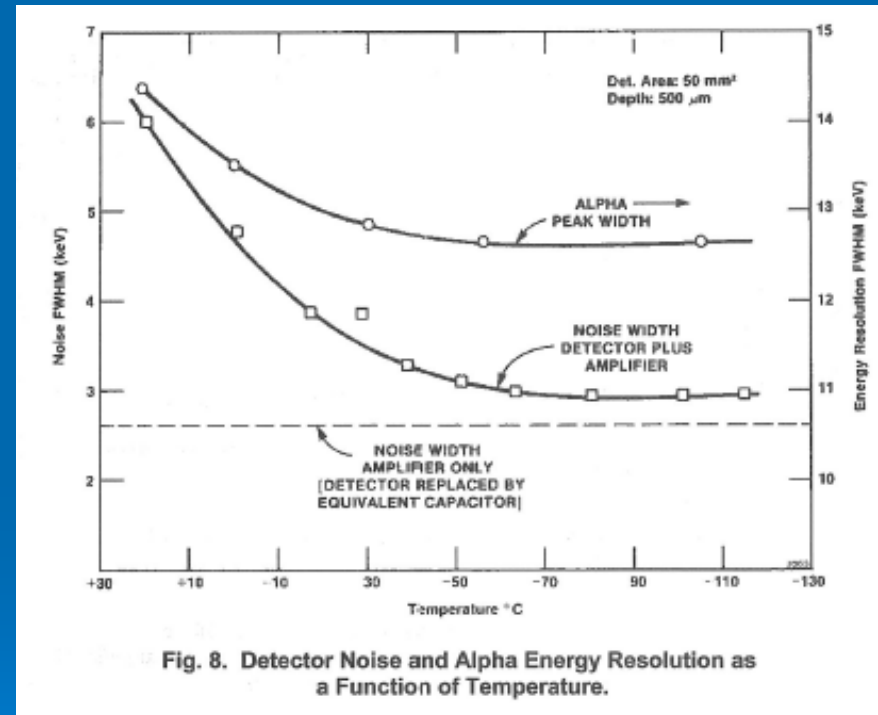
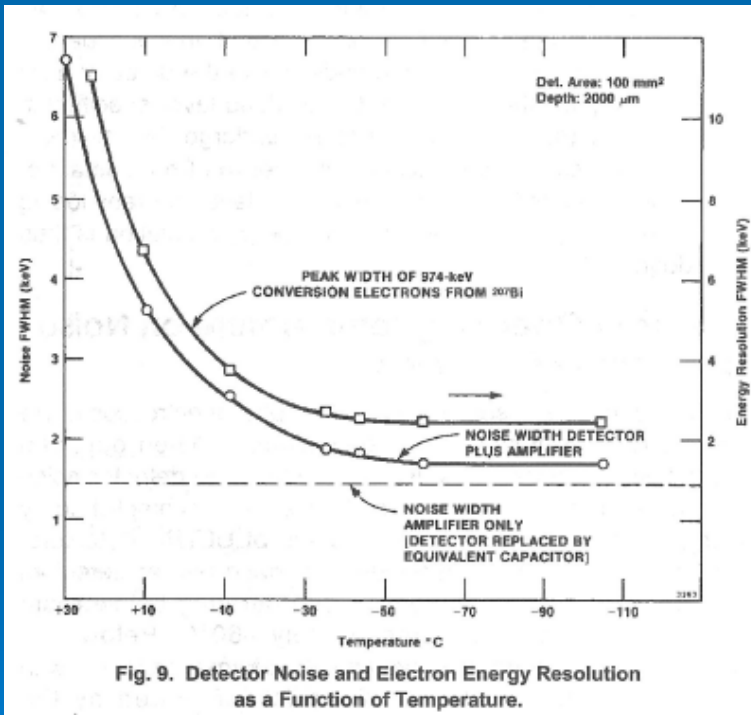


Figure 2.11 Plots showing the specific energy loss of various heavy ions in aluminum. The abscissa is the ion energy divided by its mass, and the ordinate is $-dE/dx$ divided by the density of aluminum and the square of the ion atomic number. Typical fission fragments (e.g., iodine) show a continuously decreasing $-dE/dx$ while slowing from their initial energy (~ 1 MeV/amu). (From Northcliffe and Schilling.⁸)

Multi-layer detectors enable us to identify the particles!

Energy Resolution :

[Temperature Dependence]

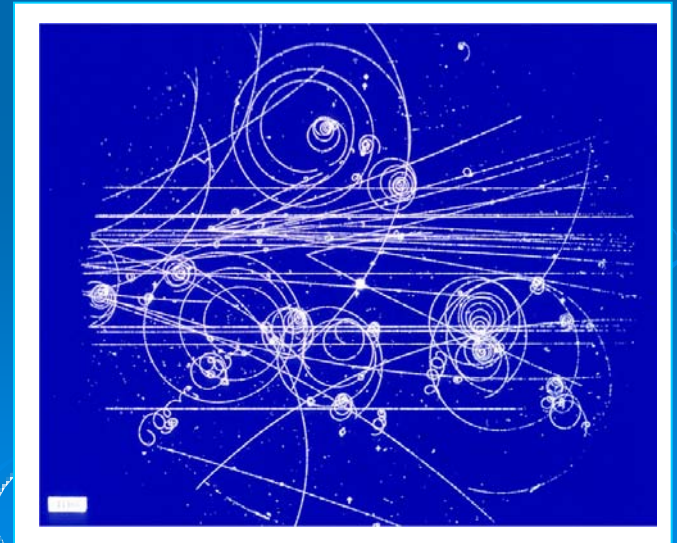


Semiconductor Detectors prefer COOLING !



Performance II

Position Measurement



Bubble chamber (CERN)

Position Measurement

Table 28.1: Typical resolutions and deadtimes of common detectors. Revised September 2003 by R. Kadel (LBNL).

Detector Type	Accuracy (rms)	Resolution Time	Dead Time
Bubble chamber	<u>10–150 μm</u>	1 ms	50 ms ^a
Streamer chamber	300 μm	2 μs	100 ms
Proportional chamber	50–300 μm ^{b,c,d}	2 ns	200 ns
Drift chamber	50–300 μm	2 ns ^e	100 ns
Scintillator	—	100 ps/n ^f	10 ns
Emulsion	<u>1 μm</u>	—	—
Liquid Argon Drift [7]	$\sim 175\text{--}450 \mu\text{m}$	$\sim 200 \text{ ns}$	$\sim 2 \mu\text{s}$
Gas Micro Strip [8]	30–40 μm	< 10 ns	—
Resistive Plate chamber [9]	$\lesssim 10 \mu\text{m}$	1–2 ns	—
Silicon strip	<u>pitch/(3 to 7)^g</u>	<i>h</i>	<i>h</i>
Silicon pixel	<u>2 μmⁱ</u>	<i>h</i>	<i>h</i>

^a Multiple pulsing time.

^b 300 μm is for 1 mm pitch.

^c Delay line cathode readout can give $\pm 150 \mu\text{m}$ parallel to anode wire.

^d wirespacing/ $\sqrt{12}$.

^e For two chambers.

^f n = index of refraction.

^g The highest resolution (“7”) is obtained for small-pitch detectors ($\lesssim 25 \mu\text{m}$) with pulse-height-weighted center finding.

^h Limited by the readout electronics [10]. (Time resolution of $\leq 25 \text{ ns}$ is planned for the ATLAS SCT.)

ⁱ Analog readout of 34 μm pitch, monolithic pixel detectors.

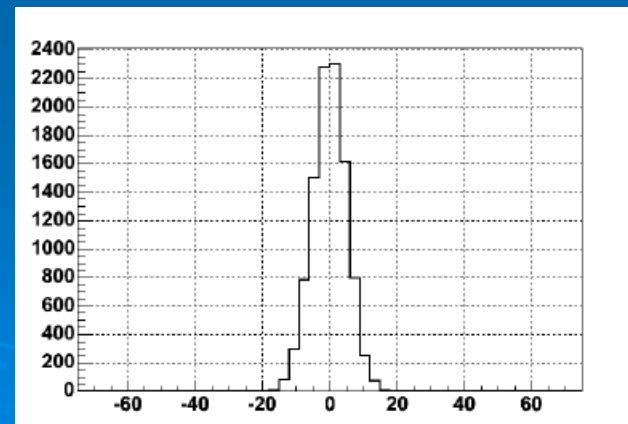
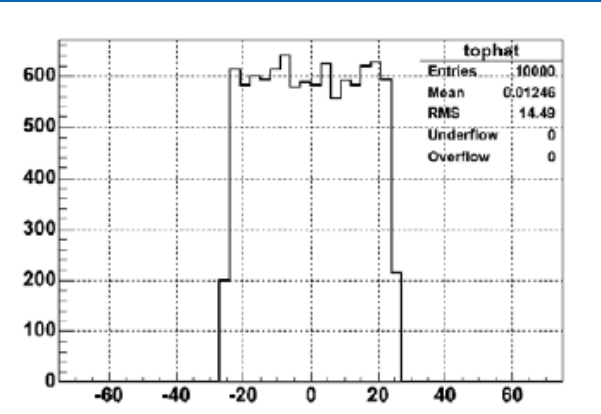
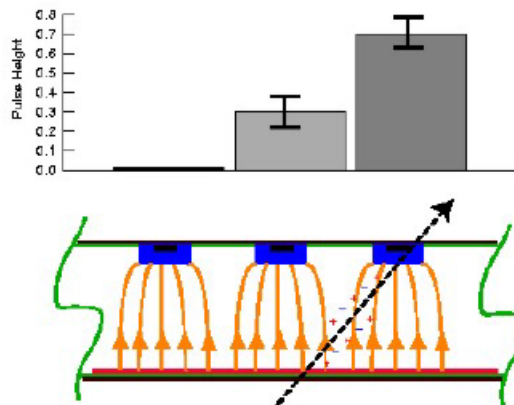
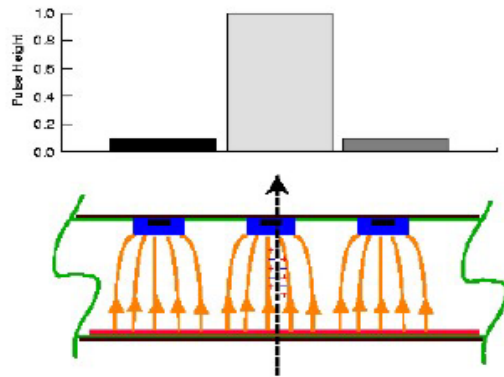
Silicon Detectors

- very good position resolution.
- works under high magnetic field.
- high rates and triggering.

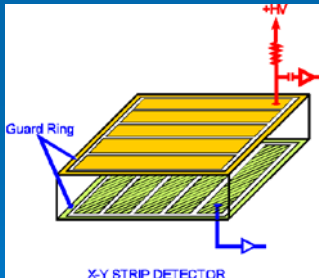
Position Measurement

$$\sigma = \text{pitch}/\sqrt{12}$$

One Strip Clusters



Position Sensitive Ge detectors



Ge detector array (GRAPE)
CNS, Univ. of Tokyo



Performance III

Timing Measurement

Silicon detector

- Electrons $\sim 10\text{ns}/300\mu\text{m}$
- Holes $\sim 25\text{ns}/300\mu\text{m}$



Timing Measurement

2. Nuclear Mass Spectroscopy by Time-of-Flight

Two silicon detectors

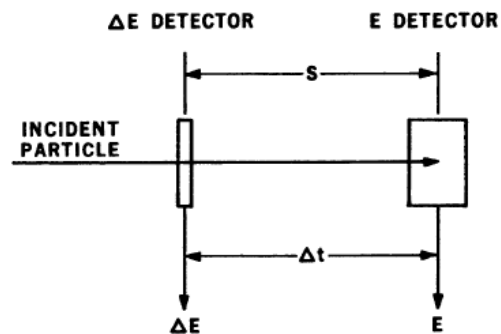
First detector thin, so that particle passes through it (transmission detector)

⇒ differential energy loss ΔE

Second detector thick enough to stop particle

⇒ Residual energy E

Measure time-of-flight Δt between the two detectors



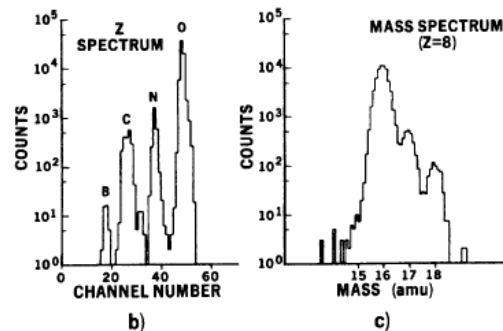
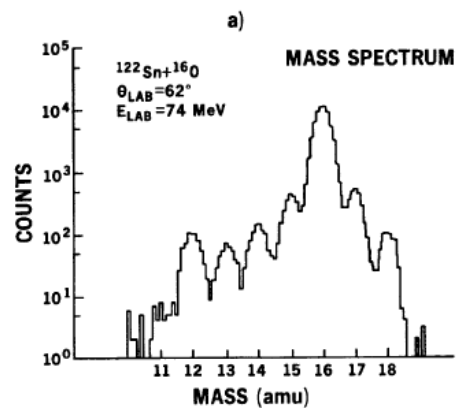
$$\begin{aligned} \Delta E + E &\rightarrow E_{TOT} \\ \Delta E, E &\rightarrow Z \\ \Delta t, E &\rightarrow A \end{aligned}$$

$$E_{tot} = \Delta E + E \quad Z \propto \sqrt{\Delta E \cdot E_{tot}} \quad A \propto E \cdot (\Delta t / s)^2$$

“Typical” Results

Example 1

Flight path 20 cm, $\Delta t \approx 50$ ps FWHM
 $\sigma_t = 21$ ps



(H. Spieler et al., Z. Phys. **A278** (1976) 241)

Electronics



Electronics

- Noise is a big issue for Silicon/Ge detectors. At 22000 e- for a 300 um thick silicon sensor, the signal is relatively small. Signal losses can easily occur depending on electronics, stray capacitances, coupling capacitor, frequency etc.
- Improve energy resolution
- Allow a low detection threshold

Electronics

[Signal Integration on Input Capacitance]

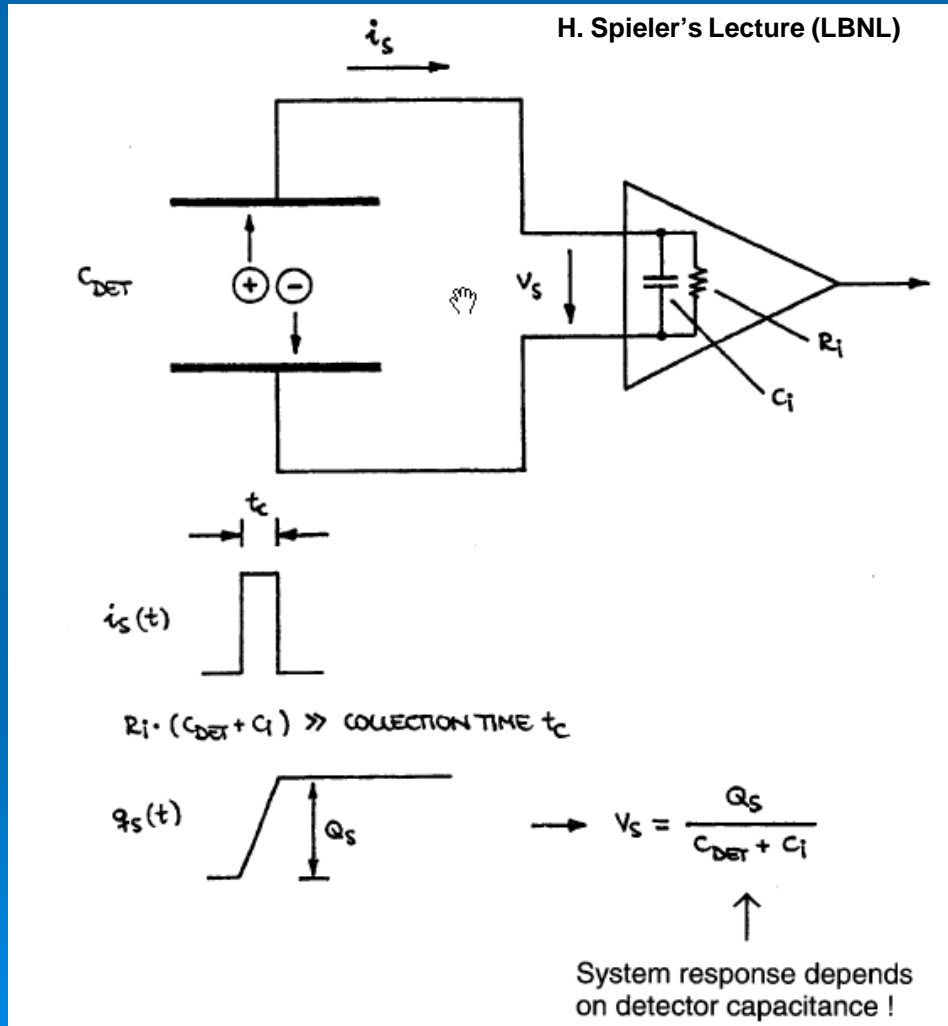
Energy Deposit \propto Charge Q_d
However,

- ☆ Detector capacitance C_{DET} may vary within a system or change with bias voltage.
- ☆ Variation of charge collection in time T_c



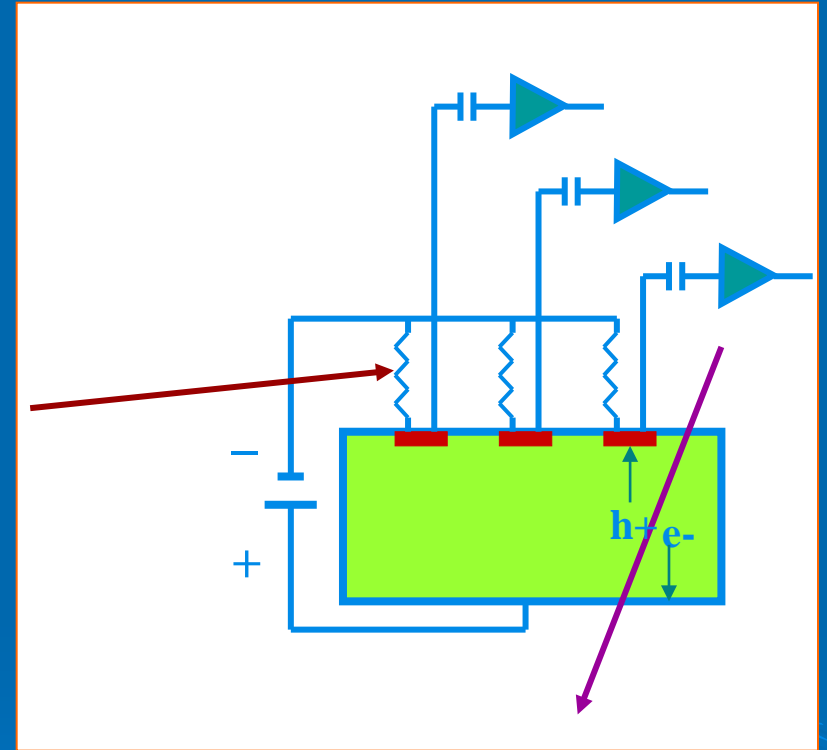
Make system whose gain (dV_{out}/dQ_s) is independent of detector capacitance.

Charge sensitive preamp !



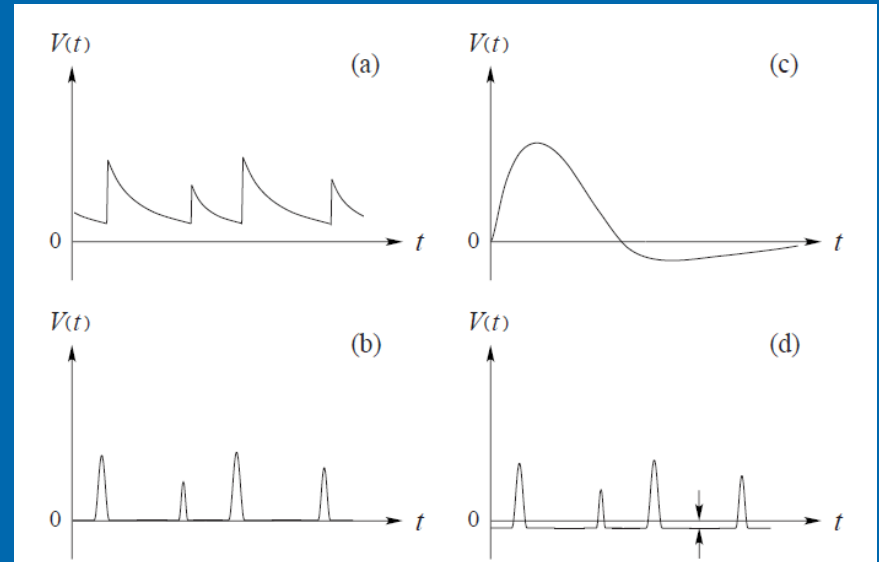
Charge Collection

- Isolation of each strip using high impedance bias connection
 - Collect / measure charge on each strip
- AC couple input amplifier (usually)
 - Avoid large DC input currents

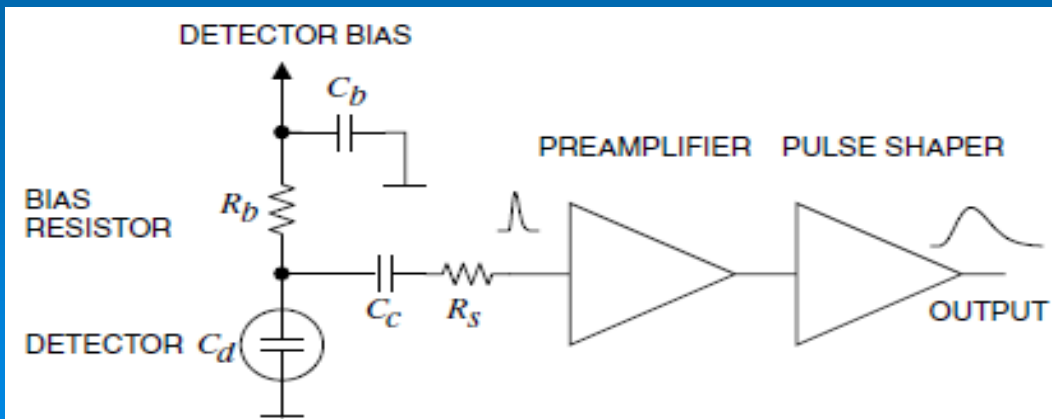


Signals

- (a) Output of preamp
- (b) Output of shaping amp
- (c) Undershoot
- (d) Base-line shift



The output of preamplifier : rapidly rising step, followed by a slow exponential decay.
Amplitude of the step = energy of the detected radiation
Exponential decay time = feedback resistor in parallel with the feedback capacitor.



Shaping Time

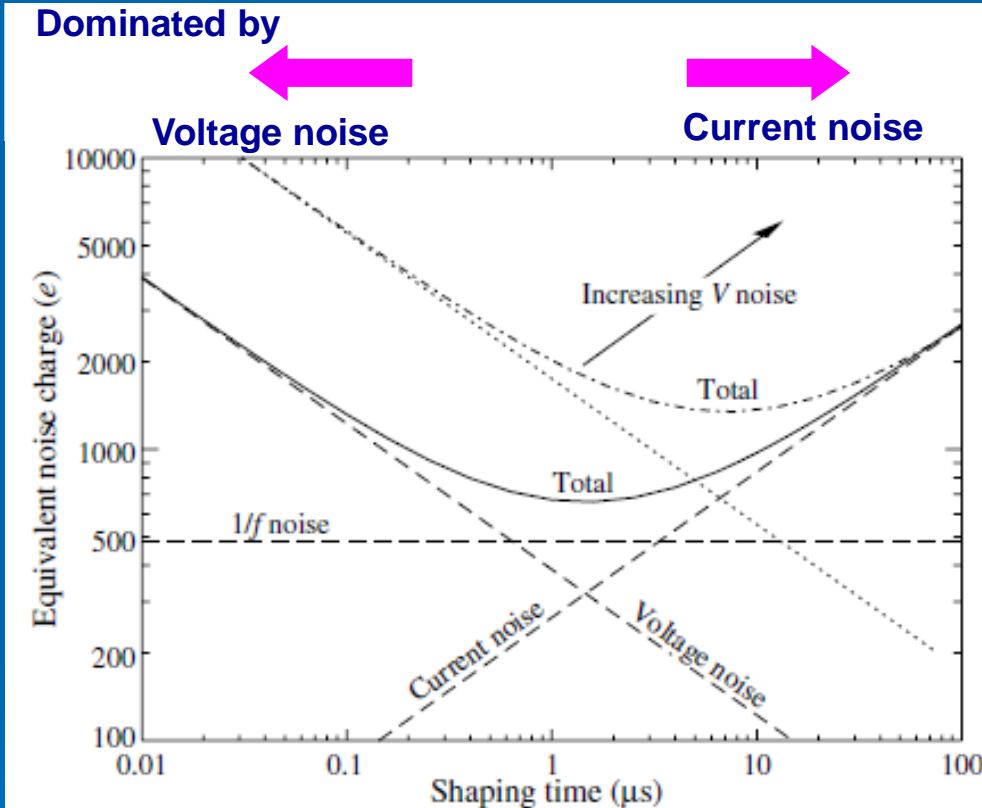


Figure 28.20: Equivalent noise charge *vs* shaping time. Changing the voltage or current noise contribution shifts the noise minimum. Increased voltage noise is shown as an example.

Optimization is required in shaping time, $\sim 1 \mu\text{s}$

Electronics : Pile-up

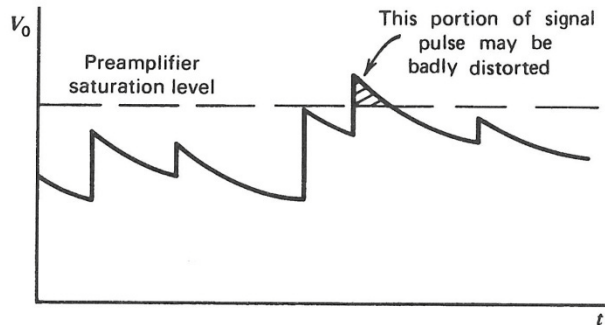
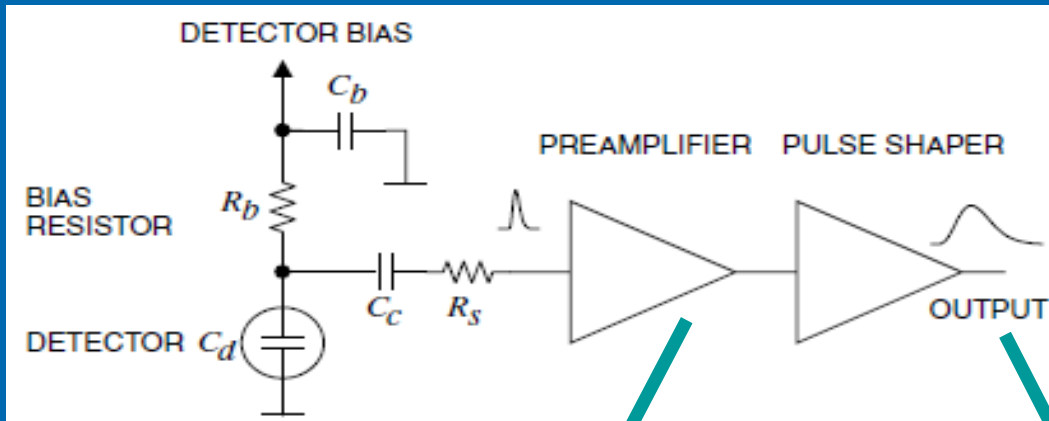
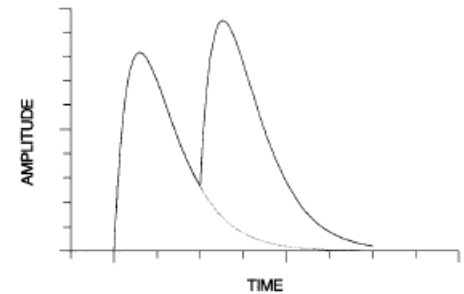
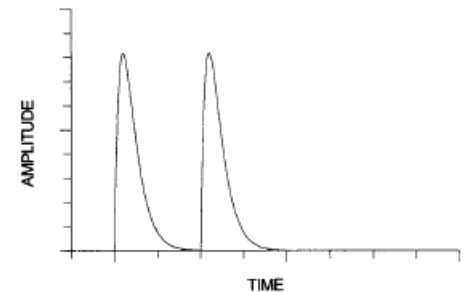


Figure 17.3 The pile-up of pulses within the preamplifier at high rates. If the saturation level of the preamplifier is exceeded, some pulses can be seriously distorted.

Pulse pile-up distorts amplitude measurement



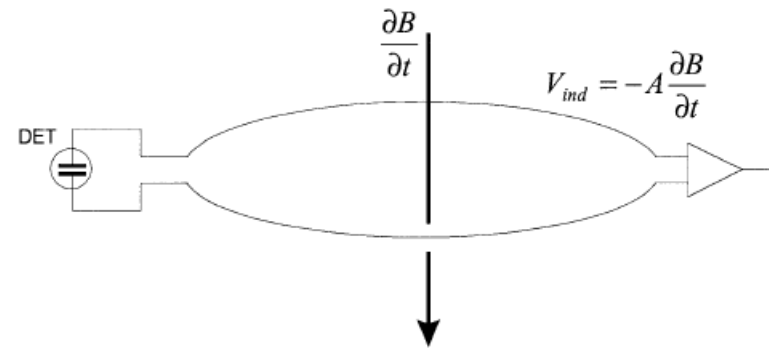
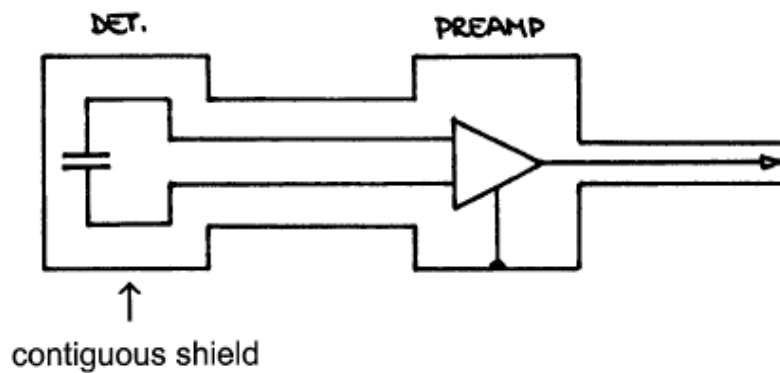
Reducing pulse shaping time to 1/3 eliminates pile-up.



Shielding and Loops

H. Spieler (LBNL)

a) Shielding



Clearly, the area A enclosed by any loops should be minimized.

Accomplished by routing signal line and return as a closely spaced pair.

Better yet is a twisted pair, where the voltages induced in successive twists cancel.

Problems occur when alternating detector electrodes are read out at opposite ends – often done because of mechanical constraints.

Operation

How to use them



Operation

DELICATE Devices

- **HV should be increased SLOWLY..**
 - Check its maximum HV value and Polarity (+/-)
 - Check the current in HV module and its signal carefully.
 - If something is wrong, stop the operation and investigate the reason.
- **Shock / vibration may destroy the detector.**
 - Careful handling.
- **Silicon detectors**
 - Only the support frame can be touched.
 - Silicon detector hates moisture.
 - Sensitive to photons (light) ... Operate in dark place.
- **Ge-detector**
 - Liquid nitrogen is required to cool the detector down.

Summary

- Semiconductor detectors based on the simple principle of the p-n junction.
- Si is typically used for charged particle & X-ray
- Ge is used for γ ray spectroscopy.

Friday afternoon, Practical training using Ge detector (by Watanabe-san)

I wish you all the best for enjoying
your stay in JAPAN !!

References

- SLAC Lecture
 - <http://www-group.slac.stanford.edu/sluo/lectures/Detector-Lectures.html>
- Silicon Detector by Paula Collins
 - <http://lhcb-doc.web.cern.ch/lhcb-doc/presentations/lectures/CollinsItacuruca03-2nd.pdf>
- REVIEW OF PARTICLE PHYSICS, Phys. Letters B 667 (2008).
- EG&G ORTEC, Modular Pulse-Processing Electronics and Semiconductor Radiation Detectors.
- GLENN F. KNOLL, Radiation Detection and Measurement.

End

谢谢。